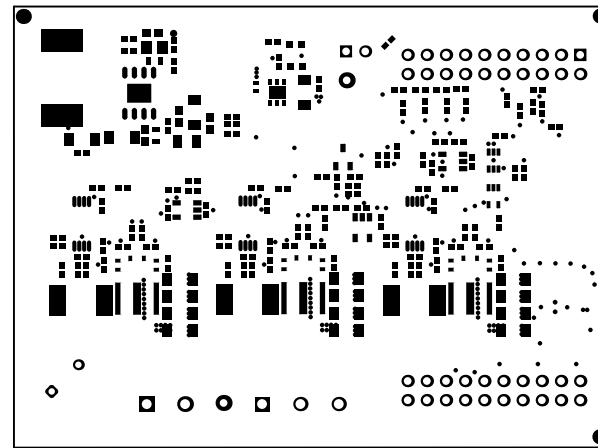
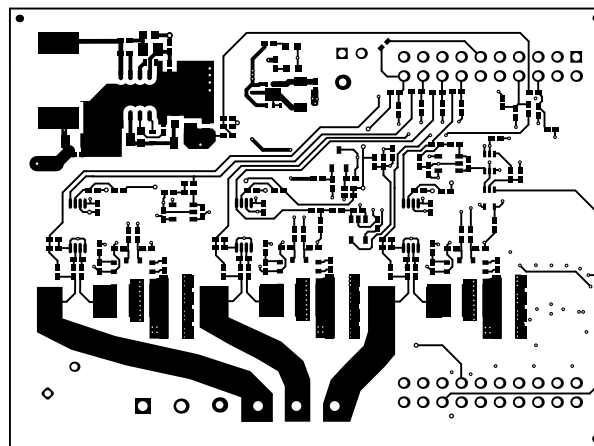


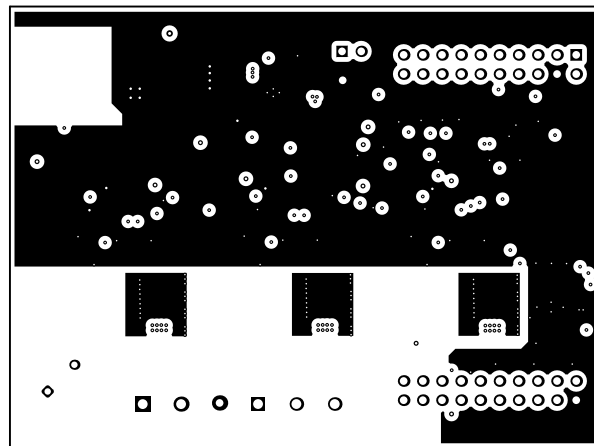
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SENS007	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: N/A		
PLOT NAME = Top Overlay	GENERATED : 6/16/2017 11:39:38 AM		TEXAS INSTRUMENTS



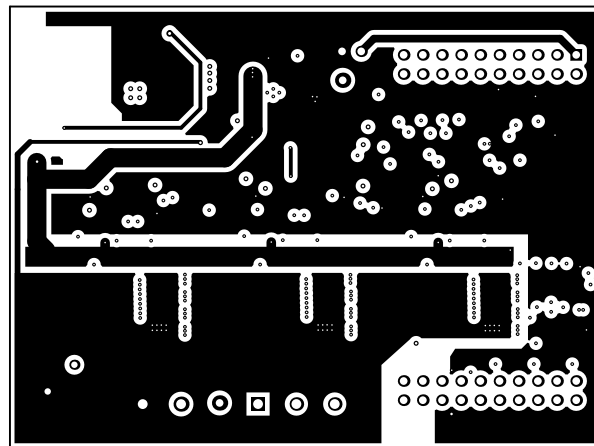
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SENS007	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: N/A		
PLOT NAME = Top Solder Mask	GENERATED : 6/16/2017 11:39:38 AM	TEXAS INSTRUMENTS	



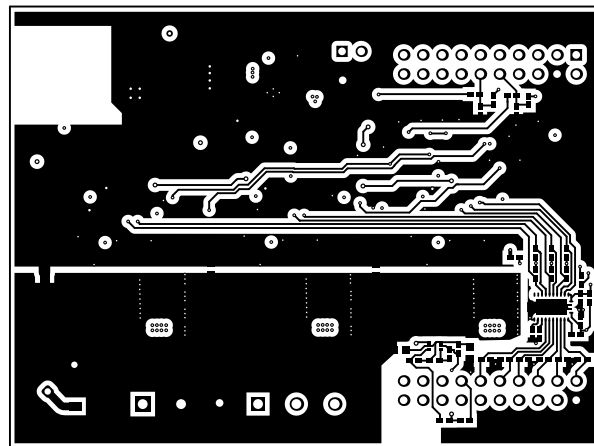
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SENS007	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: N/A		
PLOT NAME = Top Layer	GENERATED : 6/16/2017 11:39:38 AM	TEXAS INSTRUMENTS	



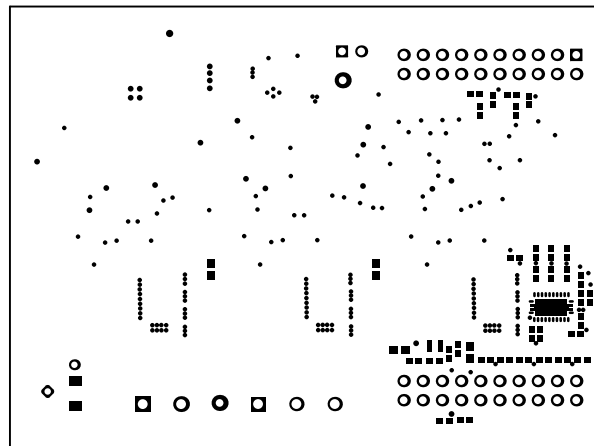
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SENS007	REV: A	SUN REV: Not In VersionControl
LAYER NAME =	TID #: N/A		
PLOT NAME = Signal Layer 1	GENERATED : 6/16/2017 11:39:39 AM	TEXAS INSTRUMENTS	



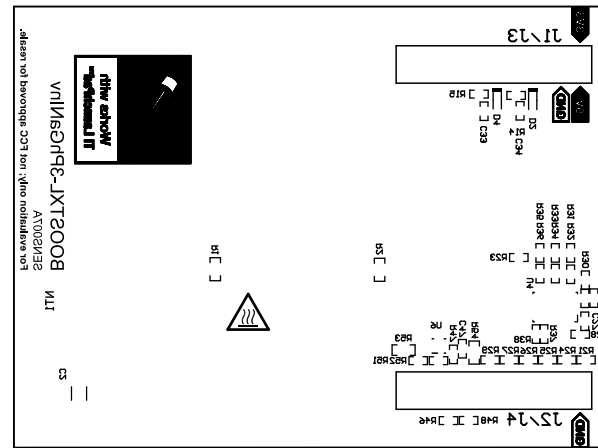
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SENS007	REV: A	SUN REV: Not In VersionControl
LAYER NAME =	TID #: N/A		
PLOT NAME = Signal Layer 2	GENERATED : 6/16/2017 11:39:39 AM	TEXAS INSTRUMENTS	



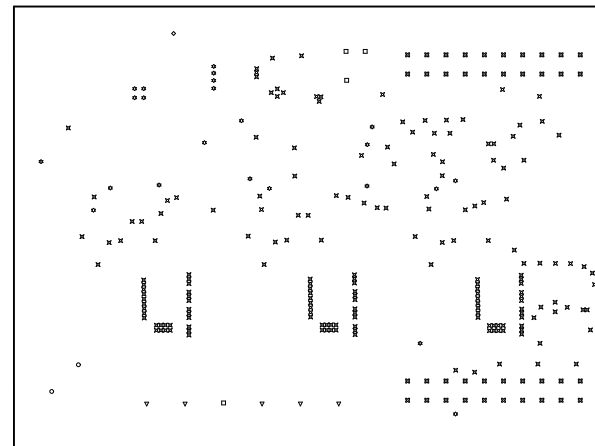
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SENS007	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: N/A		
PLOT NAME = Bottom Layer	GENERATED : 6/16/2017 11:39:39 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SENS007	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: N/A		
PLOT NAME = Bottom Solder Mask	GENERATED : 6/16/2017 11:39:39 AM	TEXAS INSTRUMENTS	

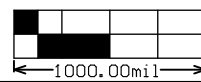


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SENS007	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: N/A		
PLOT NAME = Bottom Overlay	GENERATED : 6/16/2017 11:39:39 AM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
⊗	187	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
☆	23	12.99mil (0.330mm)	PTH	Round	Top Layer - Bottom Layer	
◇	1	16.00mil (0.406mm)	PTH	Round	Top Layer - Bottom Layer	
○	2	33.46mil (0.850mm)	PTH	Round	Top Layer - Bottom Layer	
□	4	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	40	40.16mil (1.020mm)	PTH	Round	Top Layer - Bottom Layer	
▽	5	51.18mil (1.300mm)	PTH	Round	Top Layer - Bottom Layer	
	262 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SENS007	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: N/A		
PLOT NAME = Drill Drawing	GENERATED : 6/16/2017 11:39:39 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SENS007	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: N/A		
PLOT NAME = Board Dimensions	GENERATED : 6/16/2017 11:39:40 AM	TEXAS INSTRUMENTS	

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